

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

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In re Patent Application of:  
Phillip E. Byrd et al.

Application No.: 10/649,781

Confirmation No.: 5845

Filed: August 28, 2003

Art Unit: 2812

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For: METHOD FOR TEMPORARILY ISOLATING  
A DIE FROM A COMMON CONDUCTOR TO  
FACILITATE WAFER LEVEL TESTING

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Examiner: S. D. Isaac

**AMENDMENT AFTER FINAL ACTION UNDER 37 C.F.R. 1.116**

MS AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

**INTRODUCTORY COMMENTS**

In response to the Office Action dated March 20, 2007, finally rejecting claims 37-45 and 49-52, please amend the above-identified U.S. patent application as follows:

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks/Arguments** begin on page 5 of this paper.